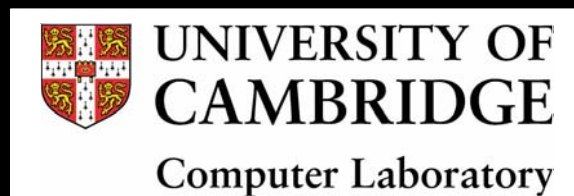

Tamper resistance and physical attacks

Part I: Introduction

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Security Group, TAMPER Lab

Structure of the talk

- Introduction
 - Physical security
 - Attack technologies
 - Security protection levels
- Attack technologies
 - Non-invasive attacks
 - Invasive attacks
 - Semi-invasive attacks
- Security evaluation and defence technologies
- Ongoing research

Introduction

- **Protection from physical attacks**
 - Protecting objects from being stolen
 - Psychological and historical background
- **Physical protection in pre-computer era**
 - Burglary (doors, locks, fences, safes)
 - Theft (guards, chains, locks)
 - Military enemy (fortification, armed guards, tanks, missiles)
- **Physical protection in computer era**
 - Military enemy (control and spying)
 - Bank fraud (PINs, plastic cards, on-line cryptography, holograms)
 - Theft (CCTV, RF tags, electronic keys)
 - Services (prepayment meters and cards)
 - Pay-TV piracy (access using smartcards)
 - GSM service (access using SIMs)
 - Software piracy (hardware dongles, crypto-coprocessors)

Introduction

- Technical progress pushed low-cost cryptoprocessors towards ubiquity
 - Car industry
 - anti-theft protection
 - spare parts
 - Accessory control
 - mobile phone batteries
 - printer toner cartridges
 - memory modules
 - Access control (tokens and dongles)
 - Home appliances (door control, entertainment)
 - Intellectual property (IP) protection (in products)
 - Software copy protection
 - Protection of algorithms
 - Protection from cloning

Levels of physical protection

- Access control
- Obstruction
- Active protection
- Sensors
 - Lid switch
 - Environment
 - Tamper detection and tamper evidence
- Software level
 - Password protection
 - Encryption
 - Protocols
- Hardware level
 - Electronics – PCB, sensors
 - Microelectronics – Silicon implementation

Area of interest

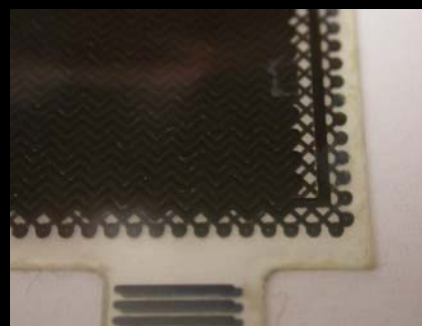
- Hardware security of semiconductor chips
 - Security modules
 - Smartcards
 - Microcontrollers
 - ASICs and custom ICs
 - Other single-chip solutions
- Do we have the same level of protection as in high-end applications?
- Do we have an adequate level of protection?

Tamper protection levels

■ Level HIGH

D.G.Abraham et al. (IBM), 1991

- Military and bank equipment
- All known attacks are defeated. Some research by a team of specialists is necessary to find a new attack. Total cost: over a million euros. Time to attack: months to years

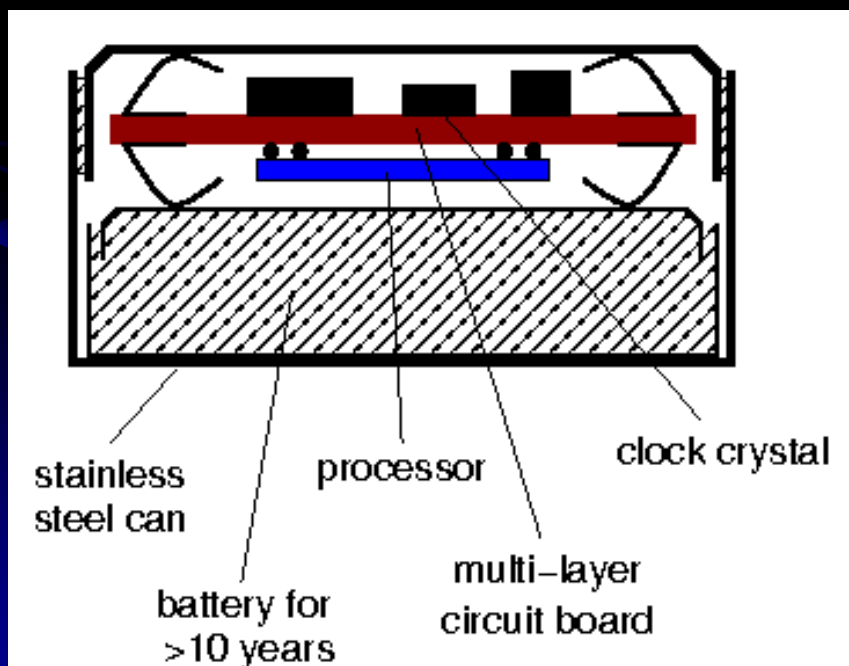


Picture courtesy of Dr Markus Kuhn

Tamper protection levels

■ Level MODH

- Secure i-Buttons, secure FPGAs, high-end smartcards and ASICs
- Special attention is paid to design of the security protection. Equipment is available but is expensive to buy and operate. Total cost: hundreds of thousand euros. Time to attack: weeks to months



Tamper protection levels

■ Level MOD

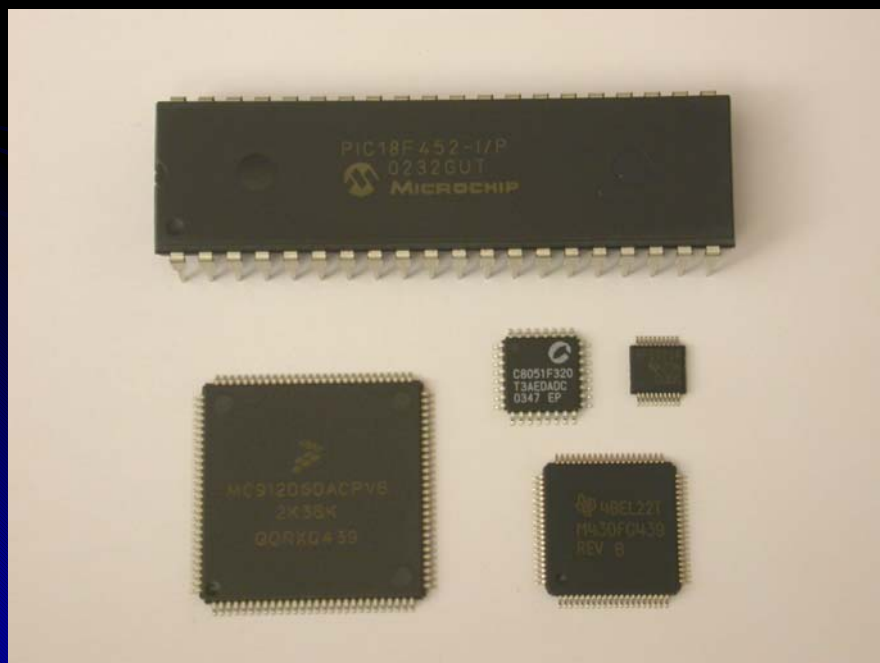
- Smartcards, high-security microcontrollers, ASICs, CPLDs, hardware dongles, i-Buttons
- Special tools and equipment are required for successful attack as well as some special skills and knowledge. Total cost: tens of thousand euros. Time to attack: weeks to months



Tamper protection levels

■ Level MODL

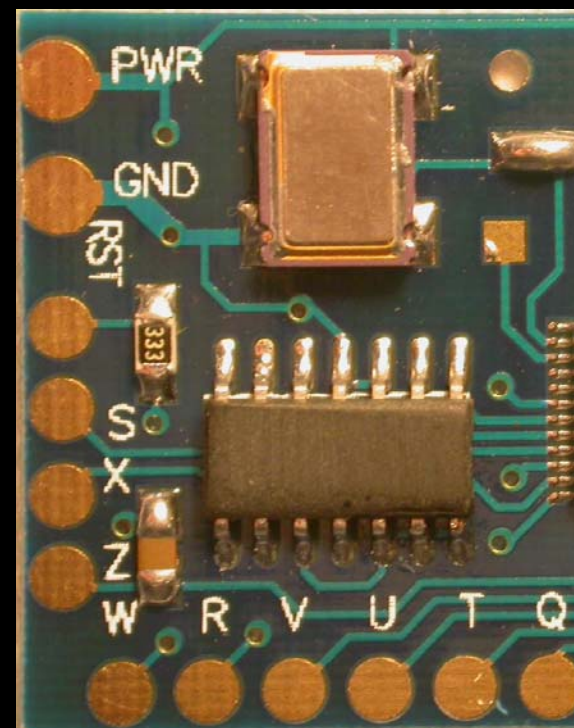
- Microcontrollers with security protection, low-cost hardware dongles
- Protection against most low-cost attacks. Relatively inexpensive tools are required, but some knowledge is necessary. Total cost: thousands of euros. Time to attack: days to weeks



Tamper protection levels

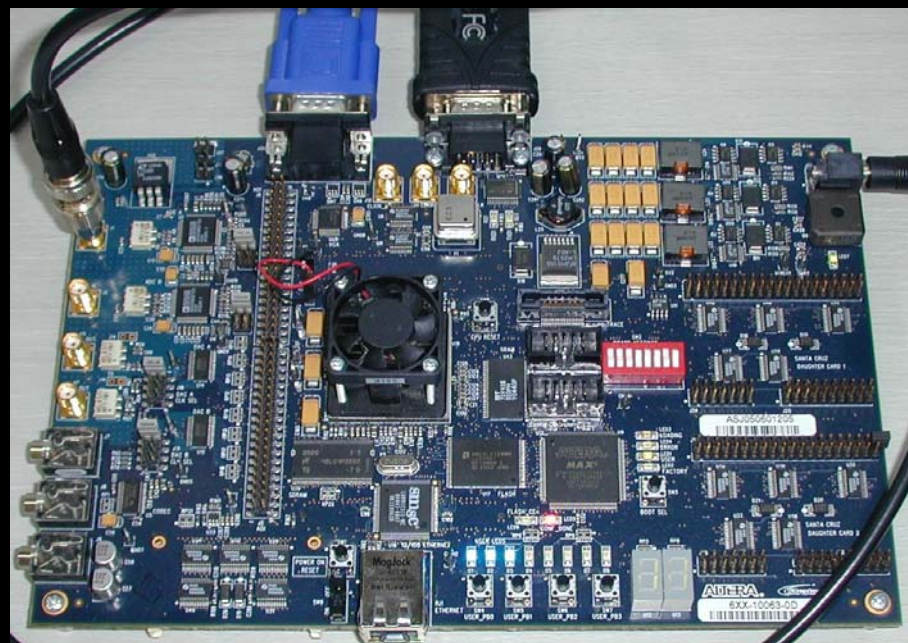
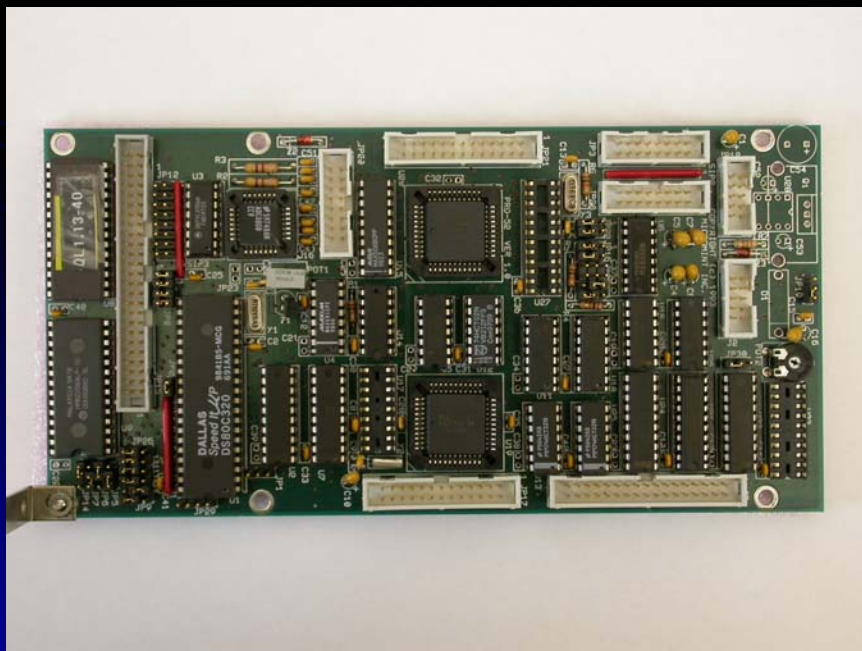
■ Level LOW

- Microcontrollers with proprietary read algorithm, remarked ICs
- Some security features are used but they can be relatively easy defeated with minimum tools required. Total cost: hundreds of euros. Time to attack: hours to days



Tamper protection levels

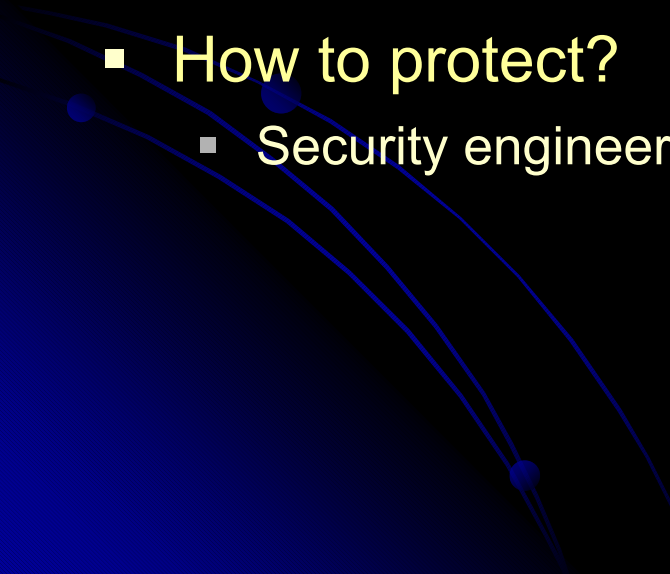
- Level ZERO (no special protection)
 - Microcontroller or FPGA with external ROM
 - No special security features are used. All parts have free access and can be easily investigated. Total cost: less than a hundred euros. Time to attack: less than an hour



Tamper protection levels

- Division of levels from HIGH to ZERO is relative
 - Some products designed to be very secure might have flaws
 - Some products not designed to be secure might still end up being very difficult to attack
 - Technological progress opens doors to less expensive attacks, thus reducing the protection level of some products
- Proper security evaluation must be carried out to estimate whether products comply with all the requirements
 - Design overview
 - Test against known attacks

Attacks and attackers

- Who is going to attacks our system?
 - Classes of the attackers
 - What tools will they use?
 - Attack categories
 - Attack methods
 - What is the reason to attack?
 - Attack scenarios
 - How to protect?
 - Security engineering
- 

Classes of the attackers

- **Class I (clever outsiders):**
 - very intelligent but may have insufficient knowledge of the system
 - have access to only moderately sophisticated equipment
 - often try to take advantage of an existing weakness in the system, rather than try to create one
- **Class II (knowledgeable insiders):**
 - have substantial specialised technical education and experience
 - have varying degrees of understanding of parts of the system but potential access to most of it
 - often have access to highly sophisticated tools and instruments for analysis
- **Class III (funded organisations):**
 - able to assemble teams of specialists with related and complementary skills backed by great funding resources
 - capable of in-depth analysis of the system, designing sophisticated attacks, and using the most advanced analysis tools
 - may use Class II adversaries as part of the attack team

Attack methods

■ Non-invasive attacks

- Observe or manipulate with the device without physical harm to it
- Require only moderately sophisticated equipment and knowledge to implement

■ Invasive attacks

- Almost unlimited capabilities to extract information from chips
- Normally require expensive equipment, knowledgeable attackers and time

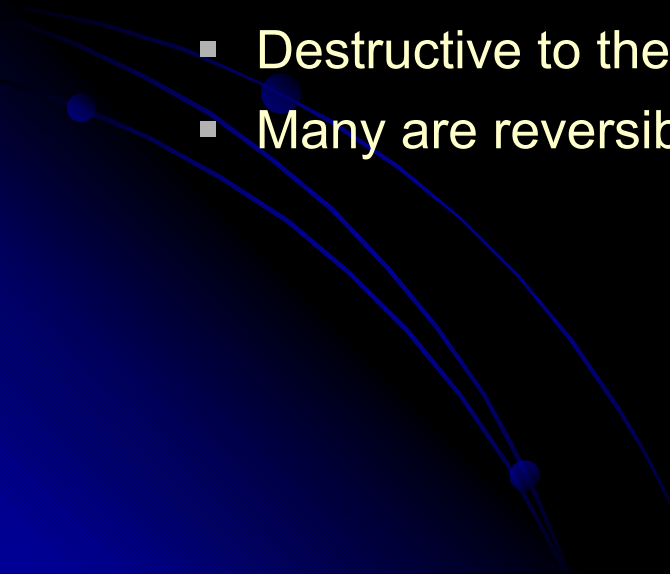
■ Semi-invasive attacks

- Chip is depackaged but the passivation layer remains intact
- Fill the gap between non-invasive and invasive types, being both inexpensive and easily repeatable

Attack categories

- **Eavesdropping (non-invasive)**
 - techniques that allows the attacker to monitor the analog characteristics of supply and interface connections and any electromagnetic radiation
- **Software attacks (non-invasive)**
 - use the normal communication interface and exploit security vulnerabilities found in the protocols, cryptographic algorithms, or their implementation
- **Fault generation (non-invasive and invasive)**
 - use abnormal environmental conditions to generate malfunctions in the system that provide additional access
- **Microprobing (invasive)**
 - can be used to access the chip surface directly, so we can observe, manipulate, and interfere with the device
- **Reverse engineering (invasive)**
 - used to understand the inner structure of the chip and learn or emulate its functionality; requires the use of the same technology available to semiconductor manufacturers and gives similar capabilities to the attacker

Tamper evidence

- **Non-invasive attacks**
 - Normally do not leave evidence of the attack
 - Many are reversible
 - **Invasive attacks**
 - Destructive, hence, leave evidence of the attack
 - Most are irreversible
 - **Semi-invasive attacks**
 - Destructive to the packaging of the chip
 - Many are reversible
- 

Attack scenarios

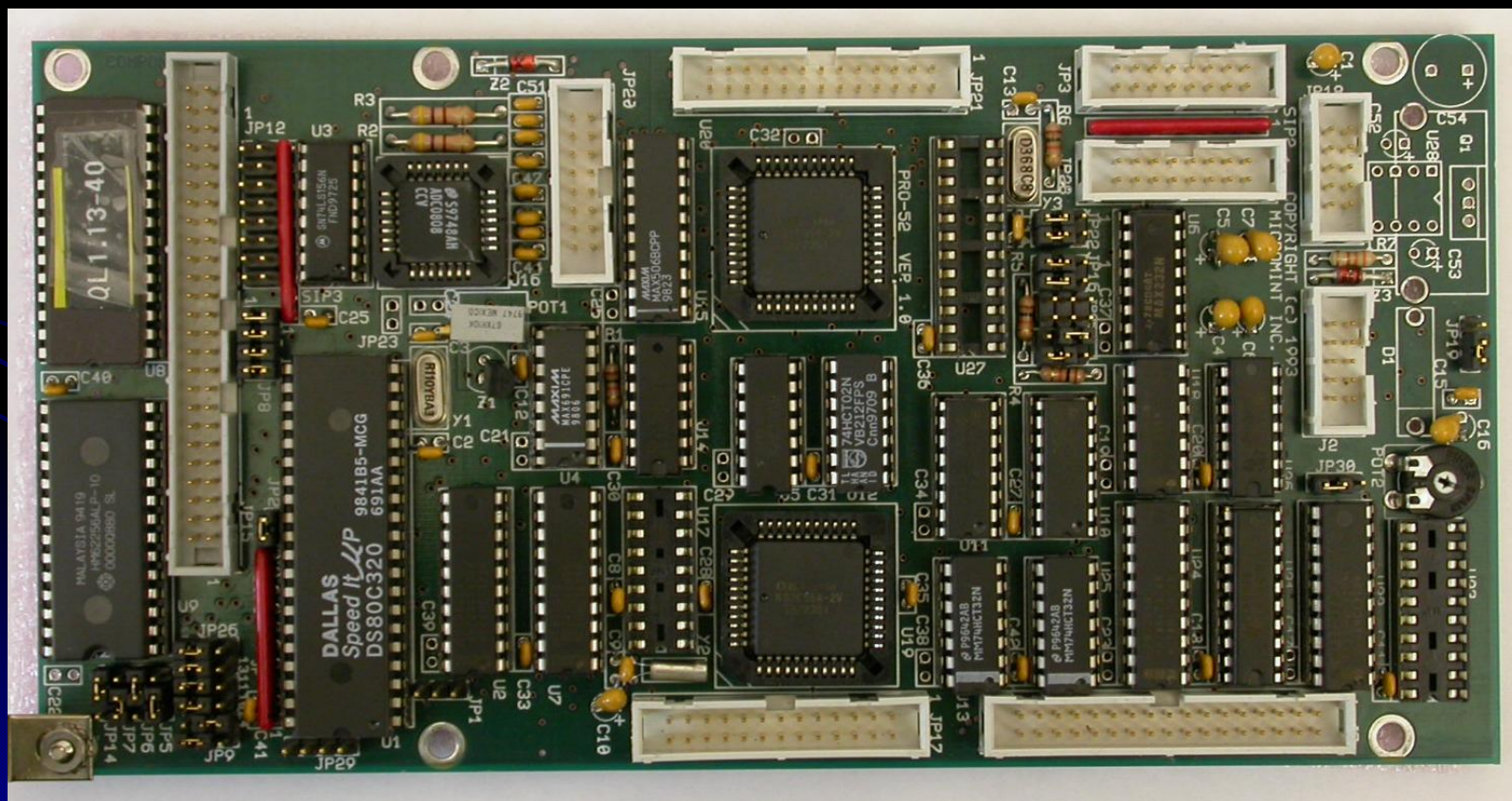
- Cloning
 - Most widely used attack scenarios (from individuals to companies)
 - Increasing sales without investment in design
- Overbuilding
 - Mass production
- Theft of service
 - Attacks on service providers (satellite TV, electronic meters, phones)
- Denial of service
 - Dishonest competition
- Decryption
 - Information recovery
 - Read cryptographic keys in plaintext
 - Force crypto keys to a known value
 - Force cryptosystem to insecure mode
- Extraction of information
 - Trade secrets and IP piracy

Security engineering

- Understanding motivations of the attackers
 - Attack scenarios
- Figuring out what to protect
 - Locating the most sensitive points (fuses, keys)
- Estimating capabilities of the attackers
 - Equipment
 - Knowledge
- Developing adequate protection
 - Hardware level (Silicon design, PCB, sensors)
 - Software level (encryption, protocols)

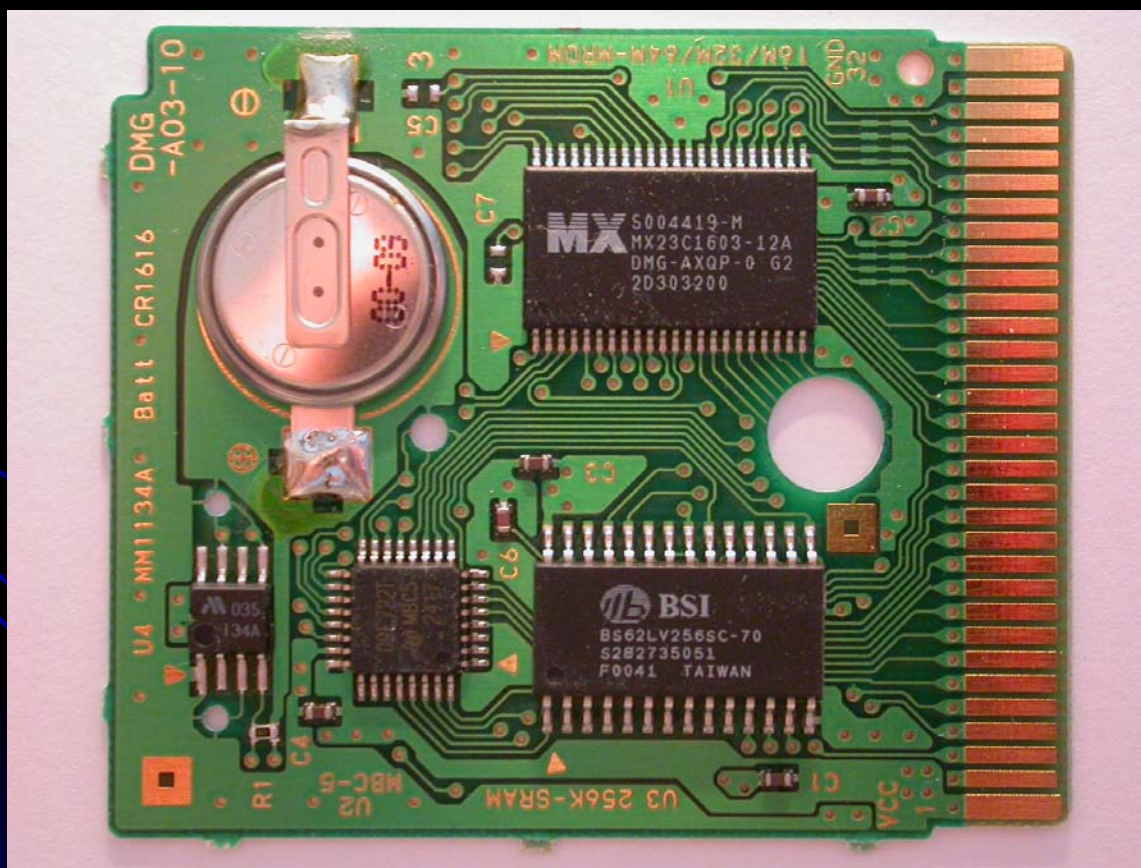
Security evolution in semiconductors

- Years 1970 – 1985
 - Tamper protection level ZERO or LOW
 - All components are easy to access and test



Security evolution in semiconductors

- Years 1980 – 1990
 - Tamper protection level LOW
 - Obscurity vs security



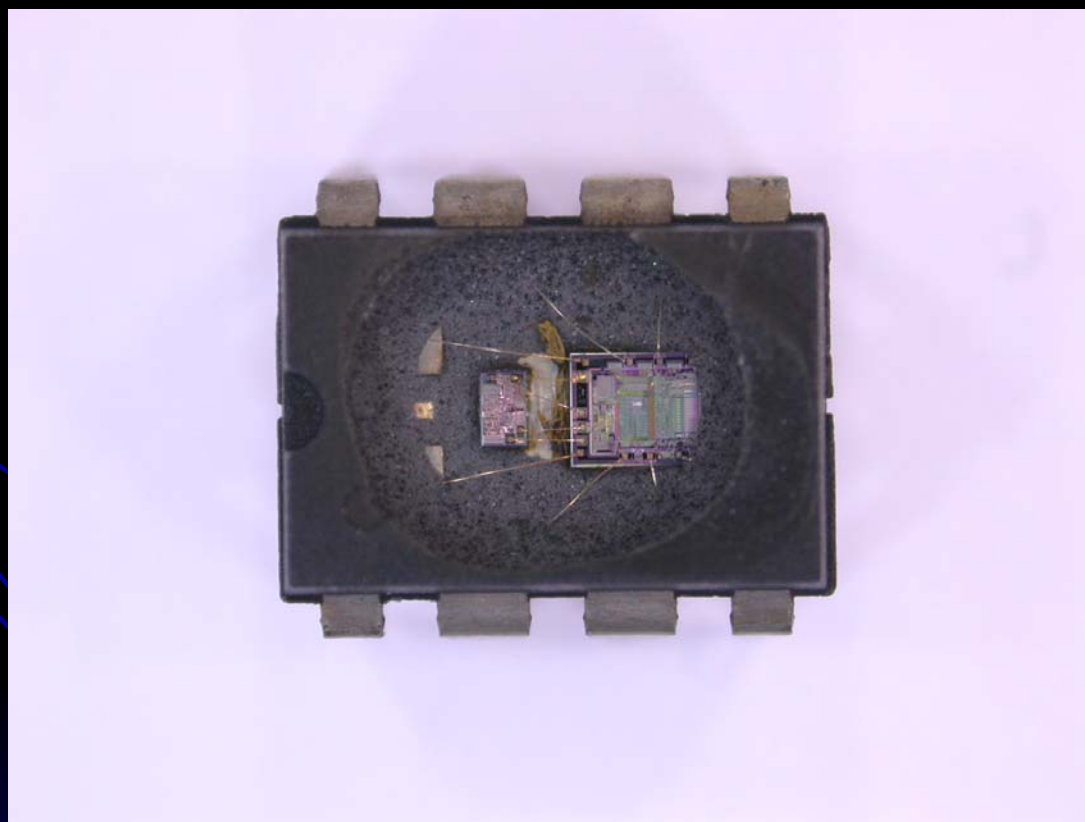
Security evolution in semiconductors

- Years 1985 – 1995
 - Tamper protection level LOW or MODL
 - No special protection used



Security evolution in semiconductors

- Years 1990 – 2000
 - Tamper protection level MODL
 - Restricted access



Microchip PIC12CE518

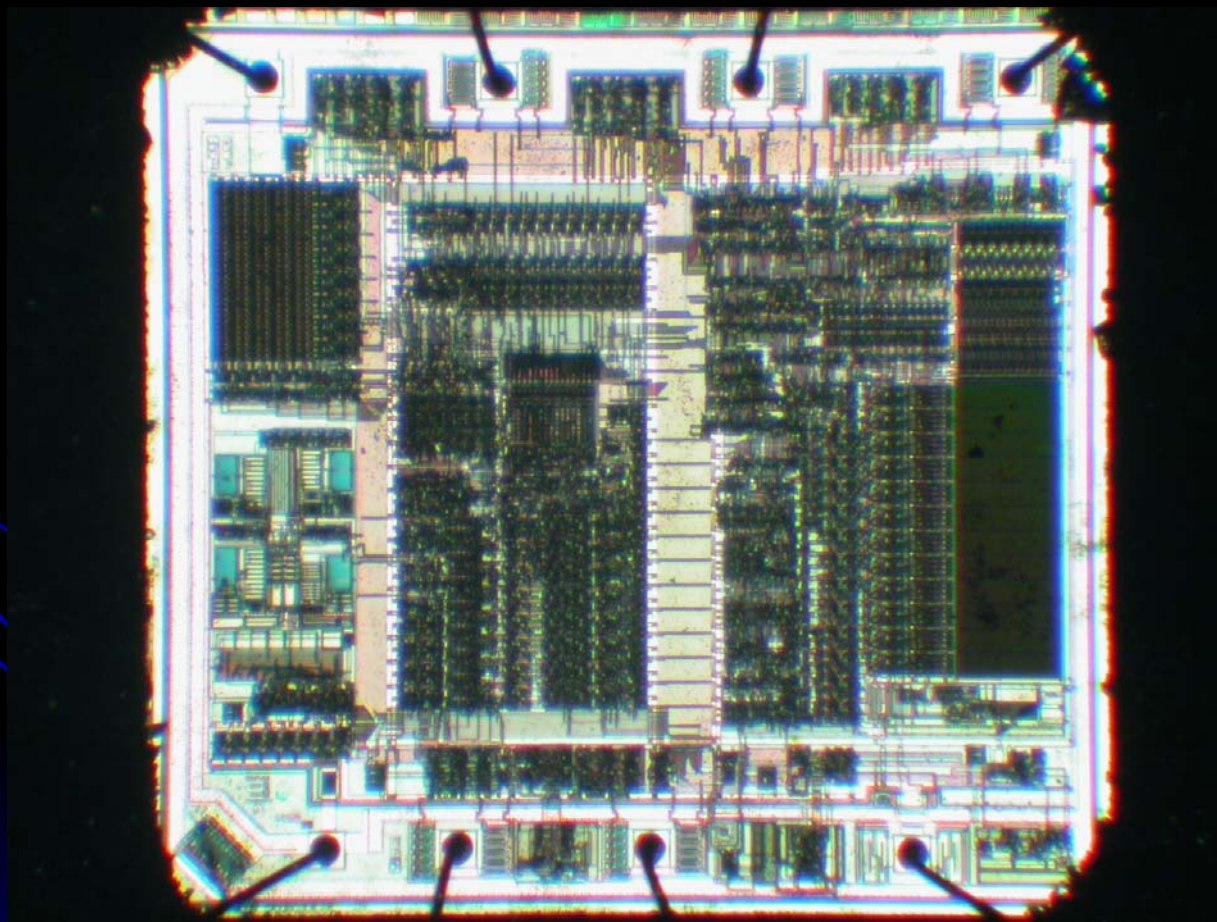
Security evolution in semiconductors

- Years 1990 – 2000
 - Tamper protection level MODL or MOD
 - Microcontrollers with security protection



Security protection in microcontrollers

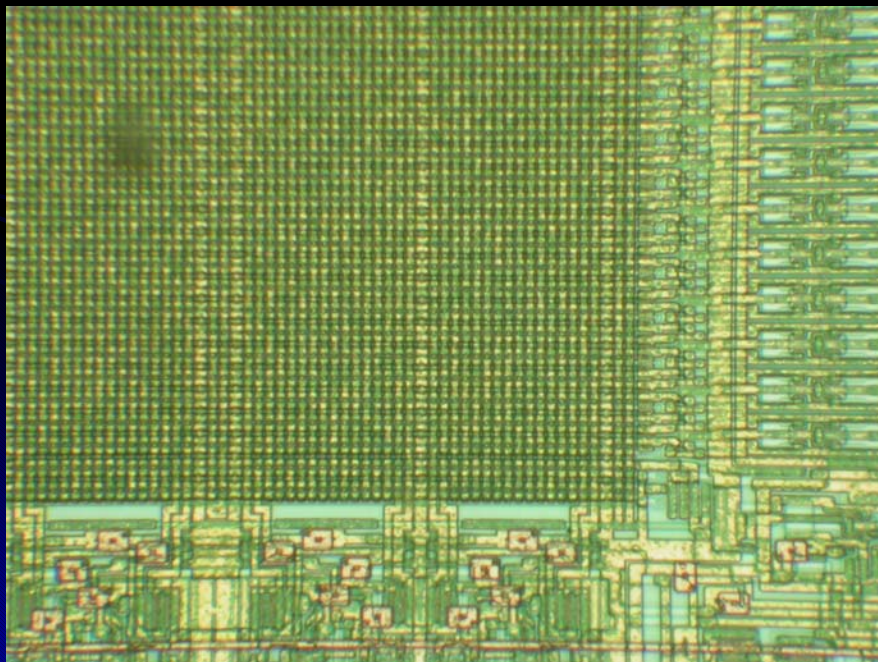
- Security fuse is placed separately from the memory array
 - Easy to locate and defeat



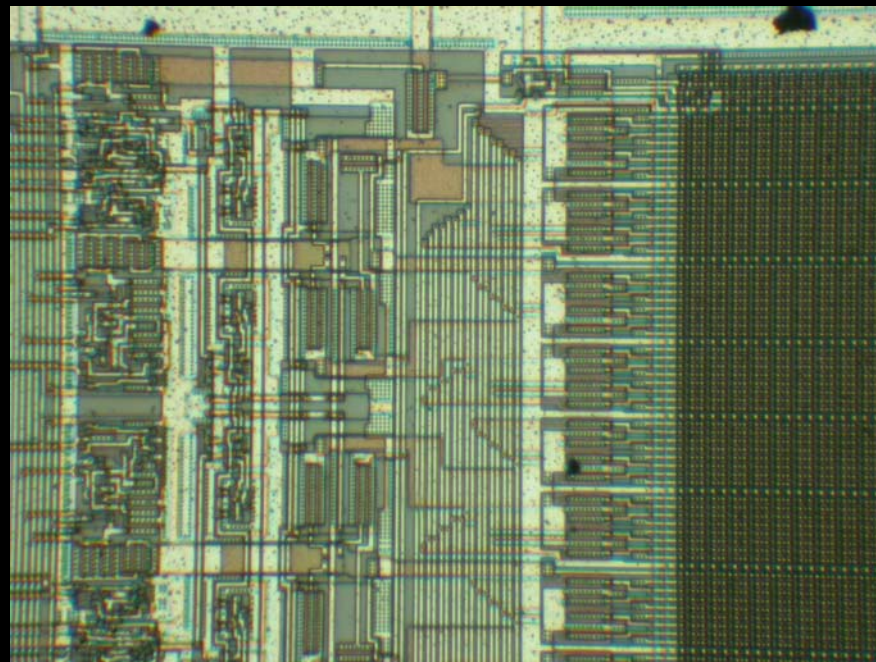
Microchip PIC12C508 microcontroller

Security protection in microcontrollers

- Security fuse is placed inside the program memory array
 - Hard to locate and defeat



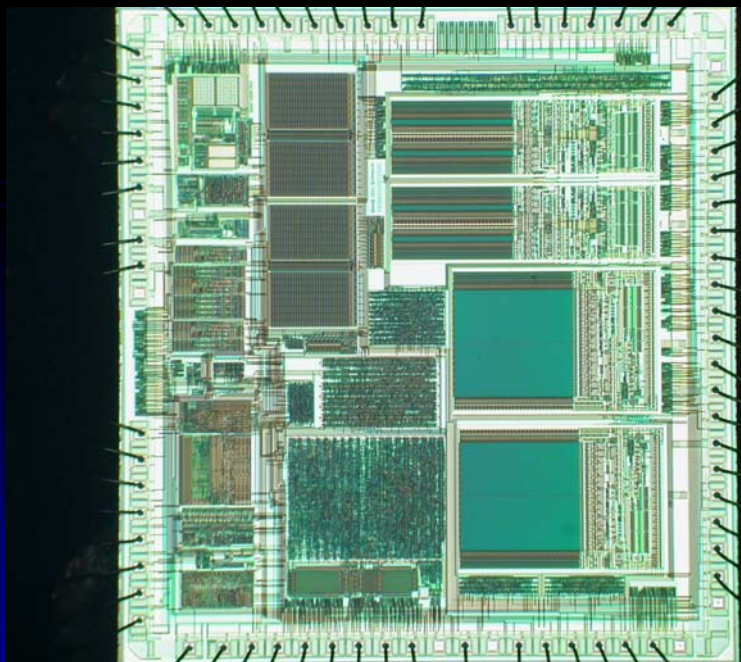
STMicroelectronics ST62T60 microcontroller



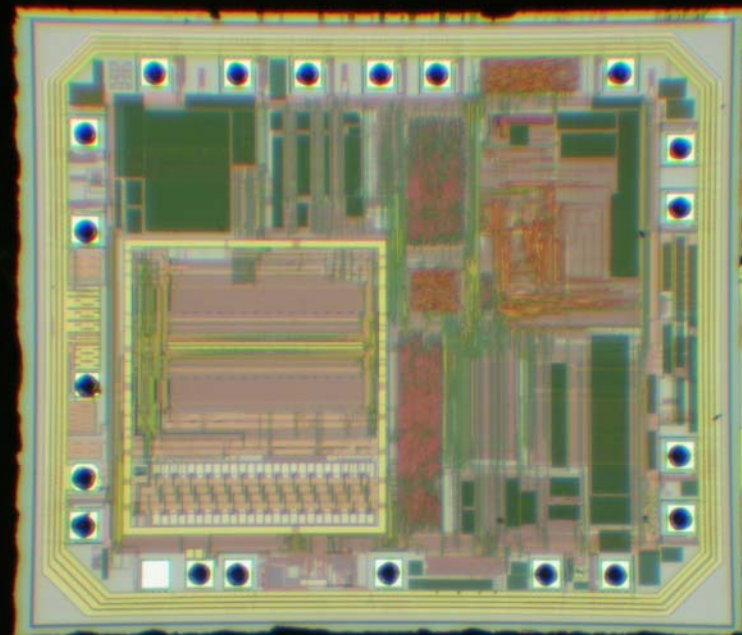
Motorola MC68HC705C9A microcontroller

Security protection in microcontrollers

- Security fuse is embedded into the program memory
 - Very hard to locate and defeat
 - Similar approach is used in many smartcards



Motorola MC68HC908AZ60A microcontroller



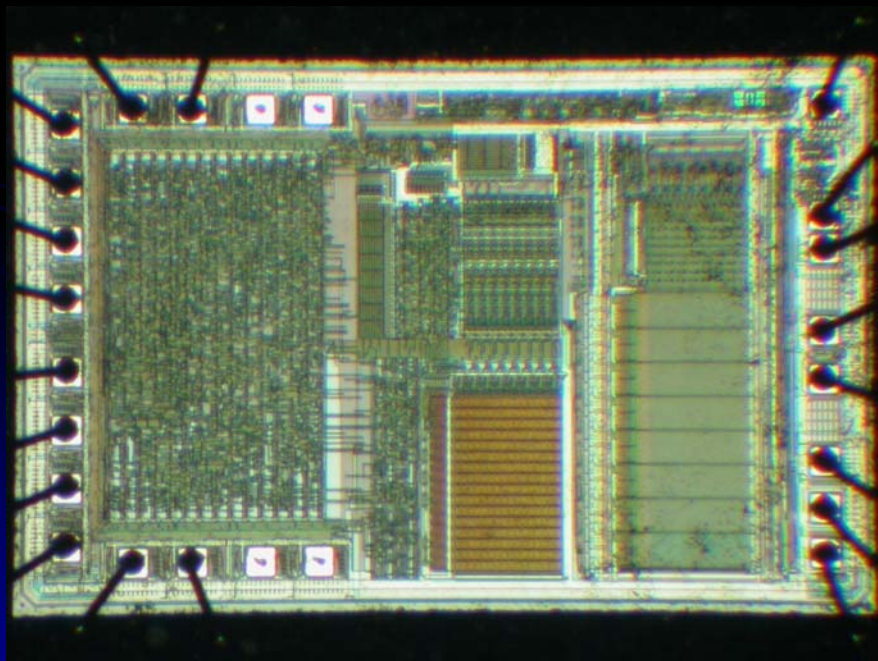
Texas Instruments MSP430F112 microcontroller

Security protection in microcontrollers

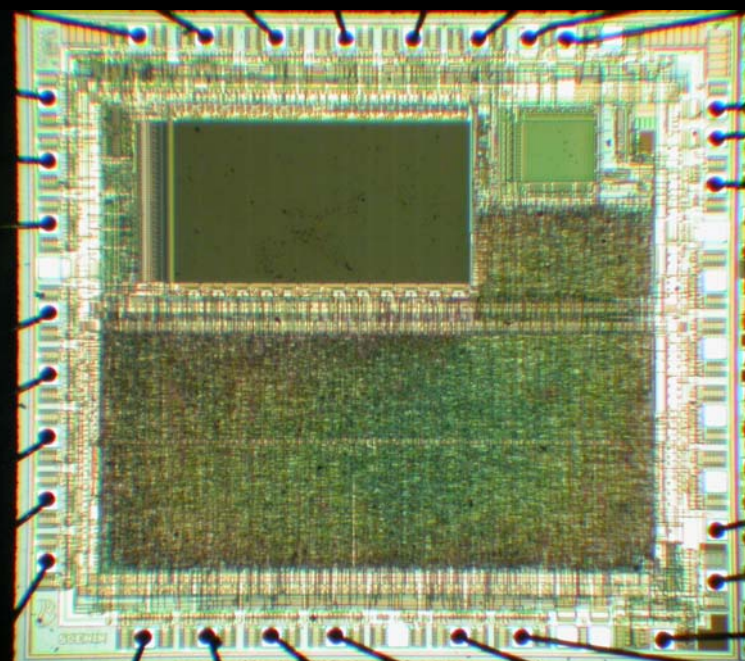
- **Monitoring of the security protection**
 - Single check on power-up or reset
 - Sensitive to glitching
 - Single check on power-up and store state in a register
 - Sensitive to glitching and fault injection
 - Check each time access is required
 - Harder to attack because of synchronization requirements
 - **Permanent monitoring**
 - Best choice for protection, however, not always convenient

Security evolution in semiconductors

- Years 2000 – 2005
 - Tamper protection level MOD or MODH
 - Glue logic design
 - used in modern microcontrollers and smartcards



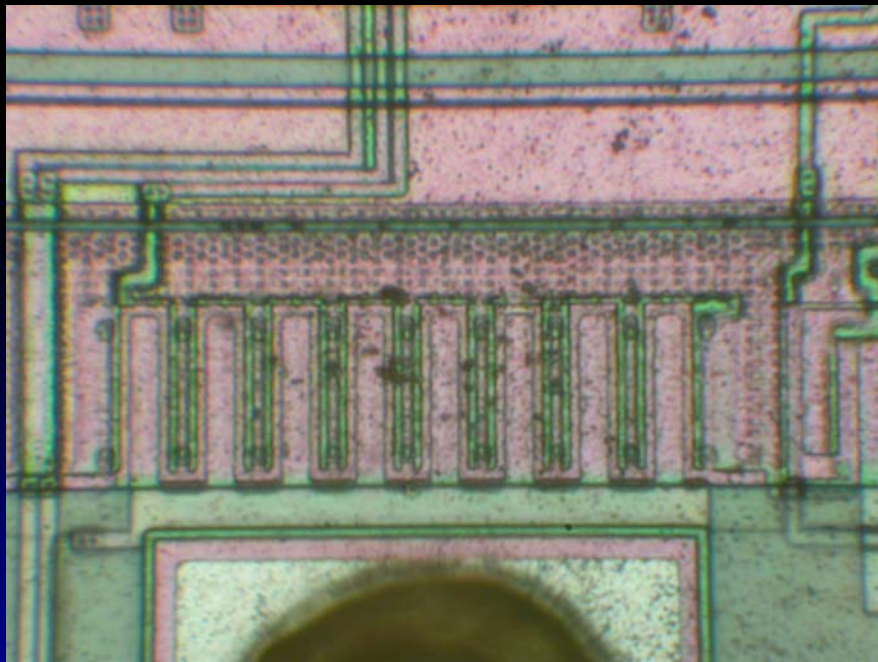
Cypress CY7C63001A microcontroller



Scenix SX28 microcontroller

Security evolution in semiconductors

- Years 1995 – present
 - Tamper protection level MOD or MODH
 - Planarisation as a part of modern chip fabrication processes (0.5 μm or smaller feature size)



Microchip PIC16F877 microcontroller



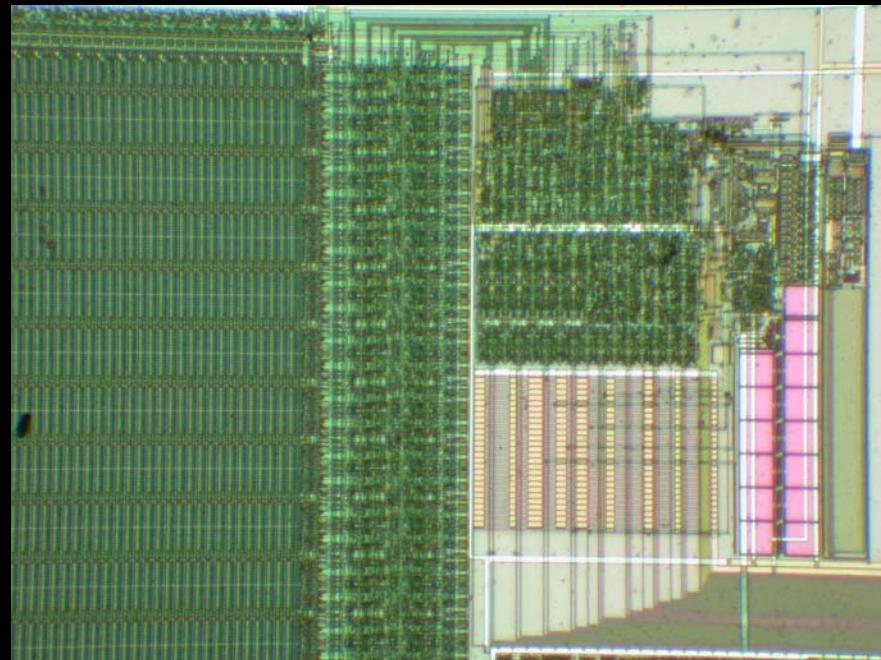
Microchip PIC16F877A microcontroller

Security evolution in semiconductors

- Years 1995 – present
 - Tamper protection level MOD or MODH
 - Bus encryption
 - Simple algorithms not to slow down the communication



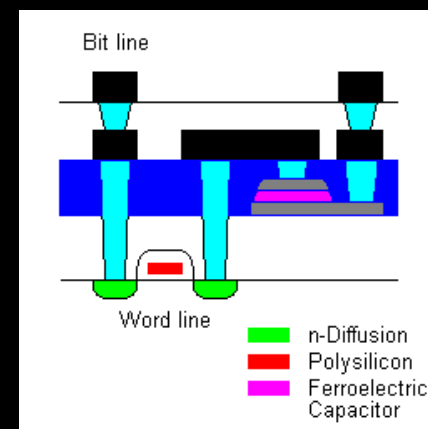
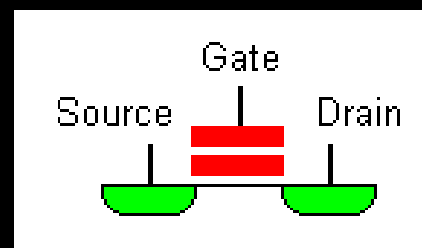
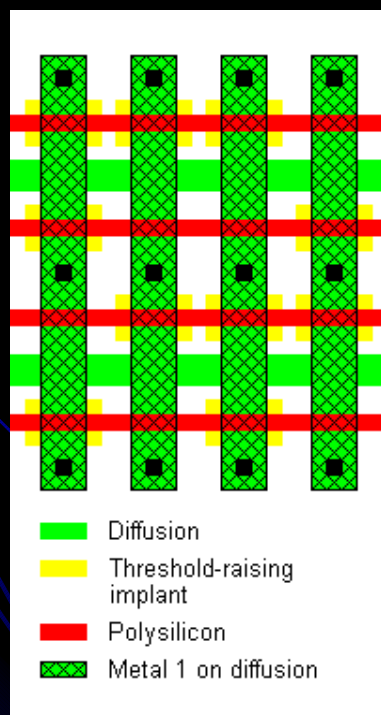
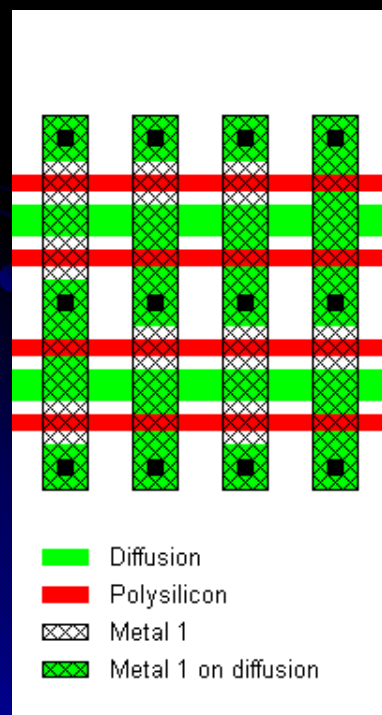
Dallas Semiconductor DS5002FP microcontroller



Infineon SLE66 smartcard

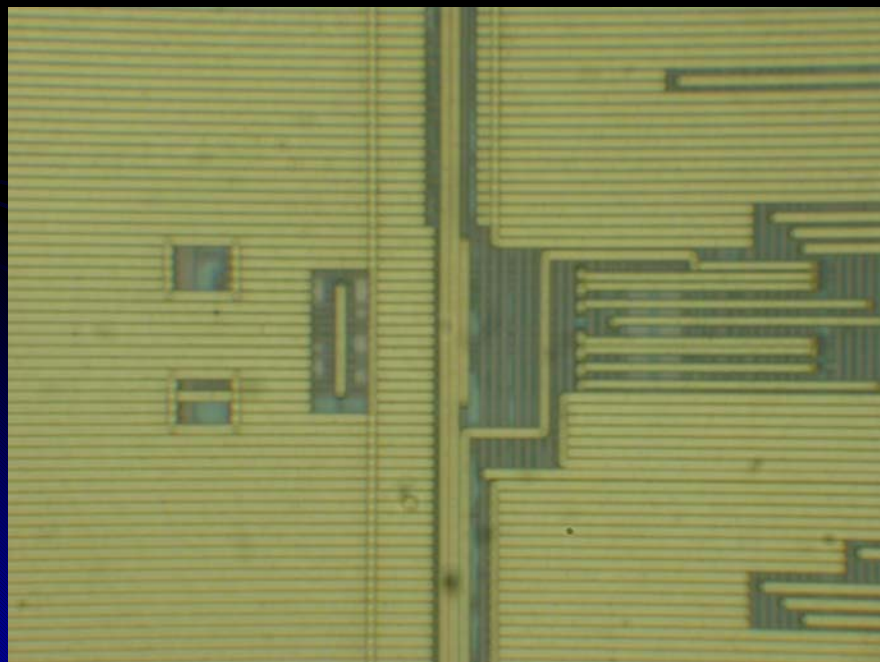
Security evolution in semiconductors

- Years 1995 – present
 - Tamper protection level MOD or MODH
 - Secure memory
 - VTROM for Mask ROM implementation
 - Flash and FRAM for non-volatile memory

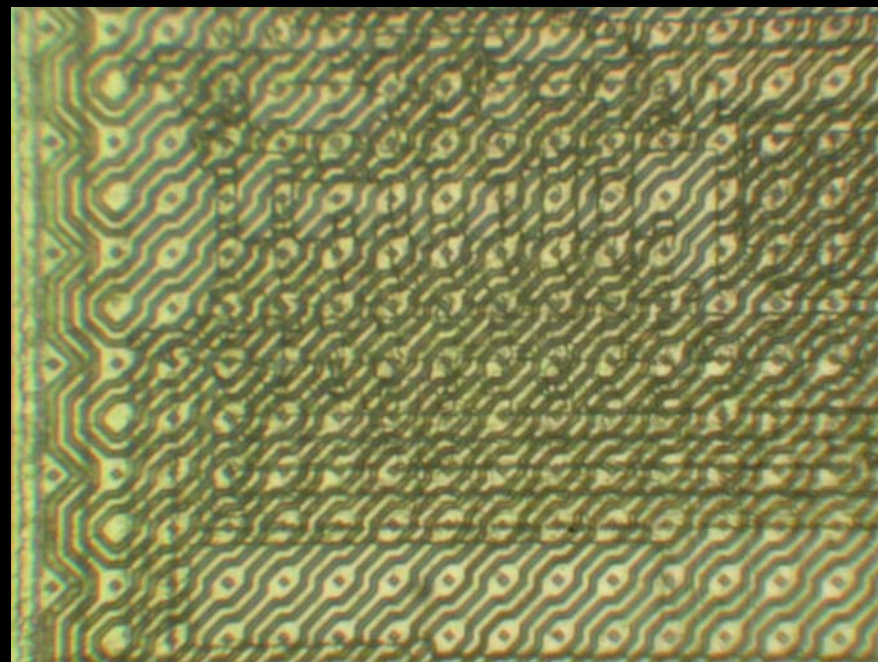


Security evolution in semiconductors

- Years 1995 – present
 - Tamper protection level MODH
 - Top metal layers with sensors
 - Voltage, frequency and temperature sensors
 - Memory access protection, crypto-coprocessors



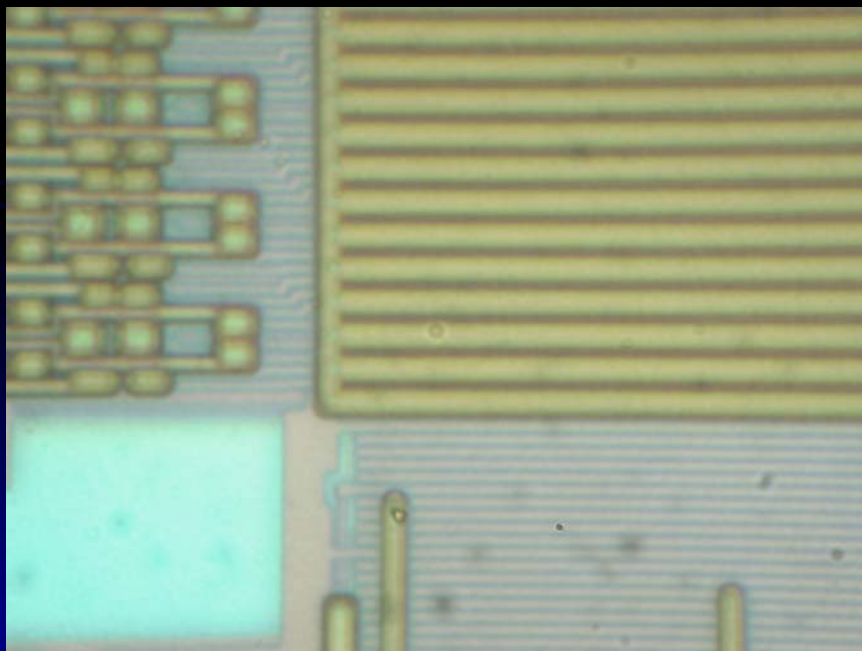
Temic T89C51RD2 microcontroller



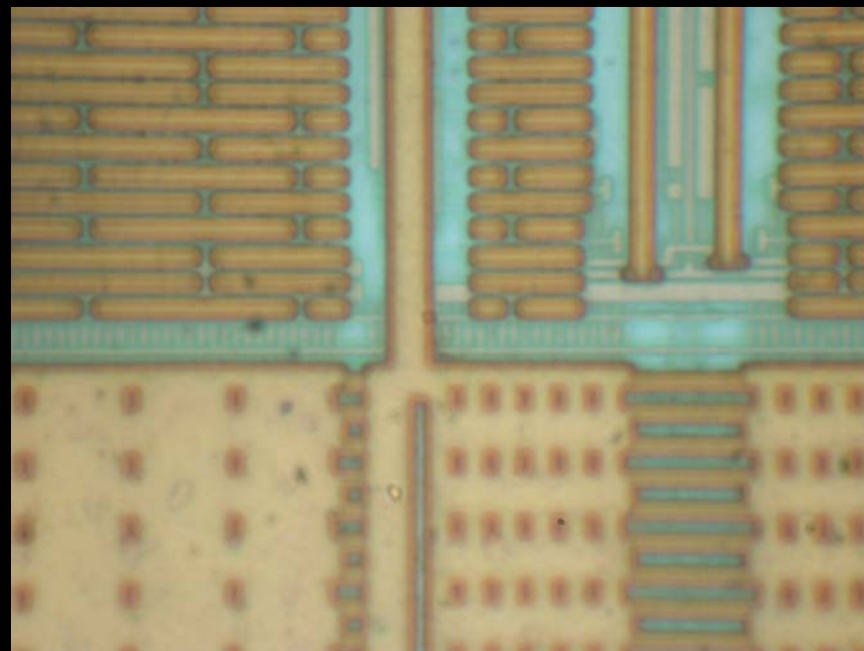
STMicroelectronics ST16 smartcard

Security evolution in semiconductors

- Impacts of technological progress
 - Size of transistors reduced to less than $0.3\ \mu\text{m}$
 - Multiple metal layers obstruct direct observation
 - Complexity of circuits significantly increased
 - More security features could be implemented



Motorola MC68HC908AP16 microcontroller



Atmel ATmega16 microcontroller

Conclusions

- There is no absolute protection – any device can be broken given enough time and resources
- Division of levels from HIGH to ZERO is relative
 - Some products designed to be very secure might have flaws
 - Some products not designed to be secure might still end up being very difficult to attack
- Proper security evaluation must be carried out to estimate whether products comply with all the requirements
- Main concern is the cost of an attack
- With technological progress it becomes more difficult to attack devices
- Attack motivations is the major driving factor in compromising security of a device
- Insiders could be potentially more dangerous as they could have more information about the devices